

Title (en)
COMPOSITIONS OF POLY(IMIDES) HAVING PHENYLINDANE DIAMINES AND/OR DIANHYDRIDE MOIETIES IN THE POLY(IMIDE) BACKBONE.

Title (de)
ZUSAMMENSETZUNGEN VON POLYIMIDEN MIT PHENYLINDANDIAMINEN UND/ODER DIANHYDRIDGRUPPIERUNGEN IM POLYIMIDSKELETT.

Title (fr)
COMPOSITIONS DE POLY(IMIDES) POSSEDANT DES DIAMINES DE PHENYLINDANE ET/OU DES MOITIES DE DIANHYDRIDE DANS LA COLONNE VERTEBRALE DU POLY(IMIDE).

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Application
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Abstract (en)
[origin: WO8604079A1] Novel compositions of a poly(imide) selected from poly(imides) having phenylindane diamine and/or dianhydride moieties in the poly(imide) backbone and a polymeric component comprising: a) a poly(etherimide); b) a poly(sulfone); c) a poly(aryl ether ketone); d) a poly(carbonate); or e) a poly(arylate); and the compositions which have been cured. The compositions are useful as adhesives, coatings and matrix resins for fiber reinforced composites. The invention also relates to a multi-layered article for use in electronic devices, the article comprising a plurality of layers each comprising a cured composition of the invention with one or more intervening layers of conductive or semi-conductive material.

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- No relevant documents have been disclosed.
- See references of WO 8604079A1

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